### Towards SC-enabled high density highly miniaturized power LED drivers: A model-centric design framework

#### PROEFSCHRIFT

ter verkrijging van de graad van doctor aan de Technische Universiteit Eindhoven, op gezag van de rector magnificus prof. dr. ir. F. P. T. Baaijens, voor een commissie aangewezen door het College voor Promoties, in het openbaar te verdedigen op woensdag ?? april 2016 om 16:00 uur.

door

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### Chapter 1

### H-SCC LED driver

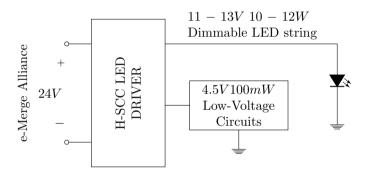


Figure 1.1: H-SCC LED driver block diagram.

An experimental converter was built with the goal to validate the performances of a H-SCC as a LED driver. The LED driver, described in the block diagram of Figure 1.1, was built using discrete components following the specifications of Table 1.1.

The driver was designed to be compliment the 24Vdc e-Merge Alliance standard used in track lighting systems, and featured two outputs. The main output supplies a LUXENON Altion LED with a maximum current of 1A with a forward voltage around 12V, thus providing 12W at full load. The secondary output is designed for low-voltage and low-power to supply other auxiliary electronic circuits. The converter efficiency was fixed to be higher than 85%, and for sake of simplicity, the switching frequency was fixed to be 2.77MHz, taking advantage of a 3dB higher tolerance of the conduced EMI standard X.

Items	Value	Unit
$v_{src}$	24	V
$v_{LED}$ voltage	11-13	V
$v_{LED}$ power	12	W
$i_{LED}$ max	1	A
$\Delta i_{LED}$	± 10	%
$v_{aux}$ voltage	4.5	V
$v_{aux}$ power	100m	W
$\overline{\eta}$	85	%
$f_{sw}$	2.77	MHz

Table 1.1: LED driver design specifications

#### 1.1 Design procedure

The LED driver is composed by two main subsystems, the power train and the close-controller. Therefore the design process is accordingly divided in three main parts: Power train design, small-signal analysis and close-loop controller design.

#### 1.1.1 Power train

Figure 1.2 shows the chosen topology for the LED driver, a 5:1 H<sup>3</sup>-Dickson driver. The chosen topology satisfies the requirements for the output voltages. The pwmnode  $v_x$  has a conversion ration of  $m_3 = \frac{2+D}{5}$ , thus providing an output voltage range between 9.6V and 14.4V considering the full range of the duty cycle D. The output regulation margins fit the load variations at maximum currents, 1A, which are between 13.2V and 11.8V for a case temperatures of -40 °C and 130 °C respectively. The dc-node has a fixed voltage conversion of  $m_{dc} = \frac{1}{5}$ , providing target voltage at  $v_a ux$  of 4.8V.

Once the topology is fixed, the next step is to size the different components, capacitors and switches. A SCC is by nature lossy, therefore the efficiency of the converter is strongly related to the selection of the right values for the components. That is why, it is essential to have an accurate model in design process of the converter. Indeed, using the algebraic expressions of the model, both, capacitors and switches can be determined as a result of an optimization process. However in the presented converter owing to the fact that it was implemented with discrete components, the flexibility in the choice of the used components was restricted to the commercial available values.

The sizing of the components was done following the procedure described in Fig-

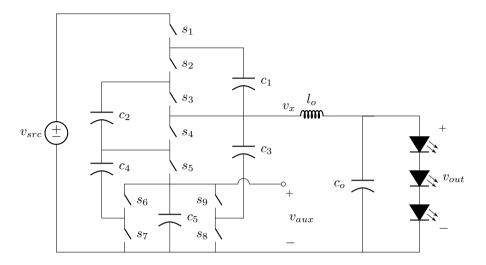


Figure 1.2: 5:1  $\mathrm{H}^3$ -Dickson LED driver for 24V e-merge track lighting application. The driver has two outputs: A 12V, 12W LED string, and 4V, 200mW to supply low power auxiliary loads.

ure 1.3, for the converter operating at full load. First, using (1.3) a target output resistance  $(r_{scc,trg})$  of the converter is computed.  $r_{scc,trg}$  was computed for an efficiency  $\eta_t rg = 90\%$ , instead of the 85% given in the specification, since this part of the design process does not take in consideration the switching losses of the transistors. Therefore a 5% overhead was given for other sources of losses, mainly switching losses. Second, the  $r_{scc}$  is composed by the output resistance of the two switching limits approximated by (1.4), thus the individual contribution of each term depends on the selected operation point of the  $r_{scc}$ . In this case, the operation point was fixed in the elbow of the curve, therefore the target equivalent output resistance for both limits, SSL and FSL, was then fixed to  $845m\Omega$ .

After this point the design process bifurcates, one path is describes the procedure to size the capacitors, and the other path to size the transistors. In either cases it have been used the algebraic expressions defined by the model,  $r_{ssl}$  equation:

$$r_{ssl} = \frac{P_{ssl}}{i_o^2} = \frac{P_{ssl}}{(f_{sw}q_{out})^2} = \frac{1}{2f_{sw}} \sum_{i=1}^{caps.} \sum_{j=1}^{phases} \frac{1}{c_i} \left[ a_i^j - D^j b_i^j \right]^2.$$
 (1.1)

is used to determine the size the capacitors, and the  $r_{fsl}$  equation:

$$r_{fsl} = \sum_{i=1}^{elm.} \sum_{j=1}^{phases} \frac{r_i}{D^j} a r_i^{j^2}$$
 (1.2)

to determine the size the transistors.

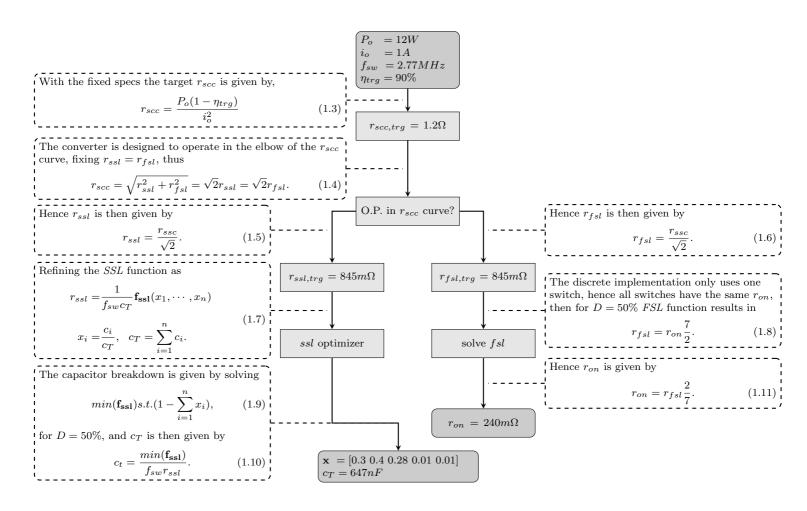


Figure 1.3: Design flow for the SCC stage.

Actually, as described in [1] minimizing both expression, results in the optimum capacitor size breakdown and switch-area breakdown, the mathematical details are given in Appendix A.1.

The capacitors values were determined using the optimization procedure described in Appendix A.2, which resulted in a total capacitance of:

$$c_T = \frac{min(\mathbf{f_{ssl}})}{f_{sw} \ r_{ssl}} = \frac{1.51}{2.77MHz \ 845m\Omega},$$
 (1.12)

and a capacitor breakdown distribution of:

$$\frac{c_i}{c_T} = \begin{bmatrix} 0.3 & 0.4 & 0.28 & 0.01 & 0.01 \end{bmatrix}. \tag{1.13}$$

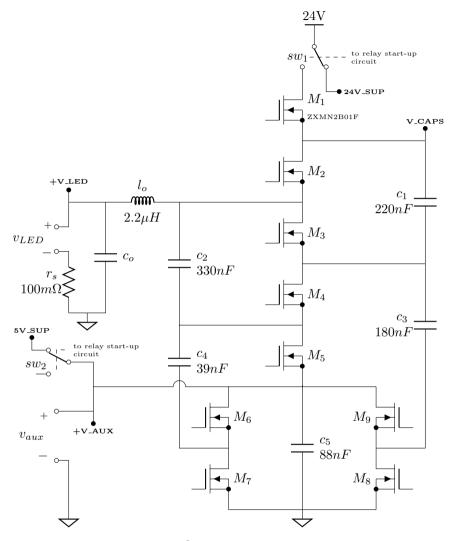


Figure 1.4:  $5:1 \text{ H}^2$ -Dickson power train schematic.

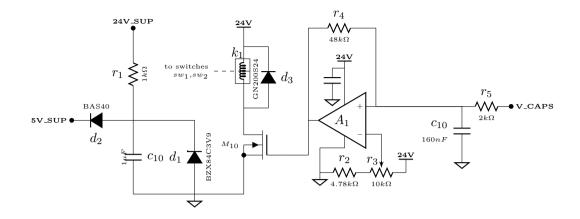


Figure 1.5: Start-up helper circuit schematic.

- 1.1.2 Small-signal analysis
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## Chapter 2

## Conclusions

# Appendices

### Appendix A

# Modeling of Switched Capacitors Converters

A.1 3:1 Dickson converter vectors

### A.2 Optimal Capacitance Breakdown

The Capacitance breakdown is obtained by minimizing the SSL impedance  $R_{ssl}$  in eq. (??). This expression can be manipulated and rewritten as a function of the total capacitance  $C_T$  of the converter

$$R_{ssl} = \frac{1}{2F_{sw}C_T} f_{ssl} \left( \vec{x} \right), \tag{A.1}$$

where:

$$X_i = \frac{C_i}{C_T} \tag{A.2}$$

$$C_T = \sum_{i=1}^n C_i. \tag{A.3}$$

In (A.1), the specific SSL impedance  $f_{ssl}$  function returns the equivalent output impedance normalized respect to the total capacitance  $C_T$  and the switching frequency  $F_{sw}$  as a function of the relative size of each capacitor, contained in  $\vec{x}$  as  $[X_1, X_2, ...]$ . Since it is proportional to  $R_{ssl}$ ,  $f_{ssl}$  is the objective function to be minimized. The optimization is constrained with the resulting function obtained from substituting (A.2) in (A.3), resulting in

$$g(\vec{x}) \to 1 - \sum X_i,$$
 (A.4)

and then the capacitance breakdown is obtained from solving

$$\min f_{ssl}(\vec{x}) \text{ subject to } g(\vec{x}) = 0 \text{ and } 0 < X_i < 1. \tag{A.5}$$

This optimization reduces the design space for the SSL impedance to only two parameters: the Switching Frequency  $F_{sw}$  and the total capacitance  $C_T$ .

#### A.3 Optimal Switch Area Breakdown

The Switch Area Breakdown is obtained by minimizing the FSL impedance  $R_{fsl}$ . Therefore eq. (??) is manipulated in order to be defined as a function of the switch area  $A_{sw}$  instead of the ON-resistance. Owing to the fact that the switch ON-resistance is inversely proportional to the switch area  $A_{sw}$  multiplied by the resistance per the unit area  $R_{\square}$  for a given switch technology

$$R_{on} = \frac{R_{\square}}{A_{SW}} \tag{A.6}$$

then  $R_{fsl}$  can be rewritten as a function of the total switch area  $A_T$  as

$$R_{fsl} = \frac{1}{A_T} f_{fsl} \left( \vec{x'} \right), \tag{A.7}$$

where

$$X_i = \frac{A_{sw,i}}{A_T} \tag{A.8}$$

$$A_T = \sum_{i=1}^{n} A_{sw,i}.$$
 (A.9)

In (A.7), the specific FSL impedance  $f_{fsl}$  function returns the equivalent output impedance normalized respect to the total switch area  $A_{\underline{T}}$  as a function of the relative size of each switch area, contained in the elements of  $\vec{x'}$  as  $[\frac{1}{X_1}, \frac{1}{X_2}, ...]$ . Since  $f_{fsl}$  is proportional to  $R_{fsl}$ , minimizing it lead to the solution with the minimum  $R_{fsl}$  per unit area. In order to obtain the switch area breakdown, the optimization is restricted to the resulting function of substituting (A.8) into (A.9)

$$g(\vec{x}) \to 1 - \sum X_i,$$
 (A.10)

thus the solution is

$$\min f_{fsl}(\vec{x'}) \text{ subject to } g(\vec{x}) = 0 \text{ and } 0 < X_i < 1.$$
 (A.11)

As in the previous case, the optimization reduces the design space for the FSL impedance to a single variable, namely the total switch Area  $A_t$ .

### A.4 Design-Oriented Optimization Result

The two converters in Fig.?? have been used to exemplify the optimization results for an SCC and an H-SCC. The presented results are valid for any load condition of the converters because the minimized functions  $f_{ssl}$  and  $f_{fsl}$  are given by the converter topology and the duty cycle. The results are presented for the two boundary operation modes: SSl and FSL; the first provides the Capacitance breakdown and the second the Switch Area breakdown.

For the SSL operation mode, the circuit has been tested with 4 scenarios. In the two first scenarios the converter has been designed following an Standard design with equal values for the flying capacitors  $C_1$  and  $C_2$ , and the output capacitor  $C_3$  100 times larger than the flying capacitors for one case, and 10 times larger for the other case. In the third scenario the three capacitors have the same value. The last scenario uses the results of the design-oriented optimization presented herein. The results are presented in Tables ?? and A.6 for the SCC and H-SCC respectively. In both cases the optimized solution achieves the lowest value of the specific impedance  $f_{ssl}$ , thus the highest efficiency for the same total capacitance  $C_T$ . However this improvement comes with a higher voltage ripple compared to the other scenarios. Actually in the two first scenarios the output capacitance is fixed, following the general rule of thumb of making them between 10 to 100 times larger than the flying capacitors, and

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therefore the value of  $C_3$  is not accurately optimized and increases the *redistributed* charge flow as described in [?]. In the other two cases all the capacitances are in the same order of magnitude a fact which reduces the *charge redistribution* and improves the charge transfer efficiency.

Table A.1: Capacitance Breakdown Results for the 3:1 Dickson operating with  $V_{in}=10V,\,F_{sw}=1MHz,\,\eta=90\%,\,I_o=5mA,\,Duty=50\%,\,R_{sw}=1m\Omega$ 

Design	$f_{ssl}$	$C_T$	$\Delta V_{o,pp}$	$MIM^1$	$IPDiA^2$
	$[m\Omega FHz]$	[nF]	[mV]	$[mm^2]$	$[mm^2]$
Std. $100xC_{fly}$	22400	336.60	10	336.6	1.4
Std. $10xC_{fly}$	2430	36.40	116	36.6	140E-3
Even $C_{fly}$	375	5.63	892	5.6	22E-3
Optimized	238	3.57	2237	3.6	14E-3

Table A.2: Capacitor Breakdown Results for 3:1 H-Dickson operating with  $V_{in}=10V,\,F_{sw}=1MHz,\,\eta=90\%,\,I_o=5mA,\,Duty=25\%,\,R_{sw}=1m\Omega$ 

Design	$f_{ssl}$	$C_T$	$\Delta V_{o,pp}$	$MIM^1$	$IPDiA^2$
	$[m\Omega FHz]$	[nF]	[mV]	$[mm^2]$	$[mm^2]$
Std. $100xC_{fly}$	22400	198.2	3.73	198.2	792E-3
Std. $10xC_{fly}$	2430	27.7	3.78	27.7	110E-3
Even $C_{fly}$	375	5.1	4.07	5.1	20E-3
Optimized	238	3.5	4.45	3.5	14E-3

Table A.3: Capacitor Breakdown Results for a 3:1 H-Dickson SCC loaded at the 2nd pwm node operating with  $V_{in}=10V,\,F_{sw}=1MHz,\,\eta=90\%,\,I_o=5mA,\,Duty=25\%,\,R_{sw}=1m\Omega$ 

Design	$X_1$	$X_2$	$X_3$	$f_{ssl}$	$C_T$	$\Delta V_{o,pp}$	$MIM^1$	$IPDiA^2$
	[%]	[%]	[%]	$m\Omega FHz$	[nF]	[V]		' 
Std. $100C_{fly}$	1	1	98	23124	19820	3.73	198.2	792E-3
Std. $10C_{fly}$	8	8	83	2651	2272	3.78	27.7	110E-3
Even $C_{fly}$	33	33	33	594	508	4.07	5.1	20E-3
Optimized	58	21	1	409	350	4.45	3.5	14E-3

The total capacitance  $C_T$  has been computed for each scenario, keeping the efficiency constant to 90%. The results have been validated with a PLECS<sup>1</sup> simulation. For the SCC the waveforms of the output voltage are shown in the Fig.??. In Table ?? it can be observed that the optimized solution uses a capacitor two orders of magnitude smaller than compared to the first scenario, although the output ripple is more than two orders of magnitude large. The third scenario shows a compromise between output ripple and total capacitance. From these results we can see that in the design of a SCC loaded at the dc node, there is a trade off between the total capacitance and the output voltage ripple. For the case of the H-SCC, the voltage waveforms of the output node -the pwm floating switching node - are shown in Fig. ??. The reduction of the total capacitance presents similar behavior to the previous case with two orders of magnitude between the optimization result and the worst case scenario with an output capacitor 100 larger. However, in this case the difference in the voltage ripple is not dramatic, being just 700mV larger in the optimized solution. Since the converter supplies a current-load -inductive output the voltage ripple at this node is less relevant than for the dc node.

For the FSL operation mode, the converters have been compared between the Switch Area breakdown evenly distributed, and the optimized solution, results are shown in Table A.4. In the case of SCC; the optimized solution coincides with the even distribution. In the case of H-SCC; the optimized solution reduces the specific output impedance  $f_{fsl}$  almost 6 points, which would reduce around 20% the total switch area for a converter with the same efficiency. From the results in Table A.4 it can be observed that the switches that carry the most charge are  $S_1$  and  $S_7$ , consuming almost half of the total area. In a second term comes switches  $S_2$ ,  $S_3$  and  $S_4$  covering almost the other half of the chip, and finally the remaining surface is splitted between  $S_4$  and  $S_5$ .

Table A.4: Switch Area Breakdown Results for the 3:1 Dickson SCC loaded at the dc node <sup>1</sup> and the 3:1 Dickson H-SCC<sup>2</sup> loaded at the 2nd pwm node

Design	$X_1$	$X_2$	$X_3$	$X_4$	$X_5$	$X_6$	$X_7$	$f_{fsl}$
	[%]	[%]	[%]	[%]	[%]	[%]	[%]	$[\Omega m^2]$
SCC Opt.	14.2	14.2	14.2	14.2	14.2	14.2	14.2	10.8
H-SCC Even	14.2	14.2	14.2	14.2	14.2	14.2	14.2	31.3
H-SCC Opt.	23.1	13.4	16.5	3.8	6.6	13.4	23.1	25.4

 $<sup>^1</sup>$  Solution with Duty=50%

The presented results have been optimized for the two operation limits, nevertheless

<sup>&</sup>lt;sup>2</sup> Solution with Duty = 25%

<sup>&</sup>lt;sup>1</sup>Behavioral circuit simulator running on Matlab <sup>®</sup> \Simulink <sup>®</sup>

the combined solutions will also lead to a solution with the minimum total output impedance. Applying the optimization in a separate manner allows us to optimize the Capacitance and the Switch Area independently.

#### A.5 Conclusions

This work presents a design-oriented optimization for SCCs based on the enhanced model of current-loaded SCCs. On the one hand the results show a reduced output impedance of the converter -therefore a converter with better efficiency for the same area- for the optimized converter. On the other hand, the optimization provides the individual values of each capacitor and switch area, and reduces the design space of the converter to three variables: the switching frequency  $F_{sw}$ , the total capacitance  $C_T$  and the total switch area  $A_{sw}$ .

The presented methodology must be understood as a first approach to the overall optimization of the converter. The goal is to have a systematic methodology that obtains the minimum output impedance for a given area. This helps to encapsulate the problem of individually sizing capacitors and switches, lifting it to higher optimization level where the three remaining design variables  $C_T$ ,  $F_{sw}$  and  $A_{sw}$  are based upon other parameters, for instance switching losses, total cost, efficiency, etc.

This work also deals with two possible architectures based on SCCs, covering the stand-alone SCCs and the innovative hybrid architectures based on current-loaded converters. The results presented for the classical SCC controvert the current design rules of using very large output capacitors, emphasising the need for an optimal selection of the output capacitor based on a compromise between capacitance breakdown, efficiency and output voltage ripple. Further work can introduce the output ripple of the dc node as another constraint of the optimization. The H-SCC opens a diverse range of possibilities, such as the use of multiple outputs and duty cycle regulation. These additional possibilities lead to new challenges for the design-oriented optimization of SCCs.

Table A.5: Capacitor Breakdown Results for a 3:1 Dickson SCC loaded at the DC node operating with  $V_{in}=10V,\,F_{sw}=1MHz,\,\eta=90\%,\,I_o=5mA,\,Duty=50\%,\,R_{sw}=1m\Omega$ 

Design	$X_1$	$X_2$	$X_3$	$f_{ssl}$	$C_T$	$\Delta V_{o,pp}$	$MIM^1$	$IPDiA^2$
	[%]	[%]	[%]	$m\Omega FHz$	[nF]	[mV]	$[mm^2]$	$[mm^2]$
Std. $100C_{fly}$	1	1	98	22400	33660	10	336.6	1.4
Std. $10C_{fly}$	8	8	83	2430	3640	116	36.6	140E-3
Even $C_{fly}$	33	33	33	375	563	892	5.6	22E-3
Optimized	43	43	14	238	357	2237	3.6	14E-3

Table A.6: Capacitor Breakdown Results for a 3:1 H-Dickson SCC loaded at the 2nd pwm node operating with  $V_{in}=10V,\,F_{sw}=1MHz,\,\eta=90\%,\,I_o=5mA,\,Duty=25\%,\,R_{sw}=1m\Omega$ 

Design	$X_1$	$X_2$	$X_3$	$f_{ssl}$	$C_T$	$\Delta V_{o,pp}$	$MIM^1$	$IPDiA^2$
	[%]	[%]	[%]	$[m\Omega FHz]$	[nF]	[V]	$[mm^2]$	$[mm^2]$
Std. $100C_{fly}$	1	1	98	23124	19820	3.73	198.2	792E-3
Std. $10C_{fly}$	8	8	83	2651	2272	3.78	27.7	110E-3
Even $C_{fly}$	33	33	33	594	508	4.07	5.1	20E-3
Optimized	58	21	1	409	350	4.45	3.5	14E-3